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(54) **LIGHT-EMITTING MODULE AND METHOD OF MANUFACTURING THE SAME, DISPLAY APPARATUS**

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(57) **ABSTRACT**

A light-emitting module includes a carrier substrate, a first light-emitting circuit layer, a backboard, a mounting cavity and at least one connection member. The first light-emitting circuit layer is disposed on the carrier substrate. The backboard is disposed on a side of the carrier substrate away from the first light-emitting circuit layer and is in contact with the carrier substrate. The mounting cavity is disposed in at least one of the backboard and the carrier substrate, and an inner wall of the mounting cavity is enclosed by both the backboard and the carrier substrate. A connection member is disposed in the mounting cavity and fixedly connected to the carrier substrate and the backboard.

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